

**PRODUCT SPECIFICATION**

**6221B-UUC**

**Wi-Fi Dual-band 1x1 11ac + Bluetooth 4.2**

**Combo Module**

Version:v1.0



## 6221B-UUC Module Datasheet

Ordering Information	Part NO.	Description
	FG6221BUUC-02	RTL8821CU-VB-CG, a/b/g/n/ac +BT4.2, 1T1R+BT, 13x15mm, USB2.0, dual antenna

Customer: \_\_\_\_\_

Customer P/N: \_\_\_\_\_

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

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## Revision History

Version	Date	Contents of Revision Change	Prepared	Checked	Approved
V1.0	2021/12/06	New version	FC	LXY	QJP

## 1. General Description

### 1.1 Introduction

The 6221B-UUC is a low-cost and low-power consumption module which has all of the Wi-Fi functionalities. It is based on Realtek RTL8821CU chipset, a highly-integrated IEEE 802.11a/b/g/n/ac MAC/Baseband/RF WLAN and Bluetooth Baseband/RF single chip. For Wireless LAN (WLAN) operation, this module supports 1-stream 802.11ac solution with USB2.0 network interface controller. For Bluetooth operation, it supports Bluetooth 4.2.

6221B-UUC complies with IEEE 802.11a/b/g/n/ac standard and it can achieve up to a speed of 433.3Mbps with single stream in 802.11ac to connect to the WLAN.

This compact module is a total solution for a combination of Wi-Fi and BT technologies.

### 1.2 Description

Model Name	6221B-UUC
Product Description	Support Wi-Fi/Bluetooth functionalities
Dimension	L x W x H: 15 x 13 x 2.35 mm
Wi-Fi Interface	USB 2.0
BT Interface	USB 2.0
OS supported	Android /Linux/ Win CE /iOS /XP/WIN7/WIN10
Operating temperature	0°C to 70°C
Storage temperature	-40°C to 125°C

## 2. Features

### General

- Highly-integrated module for 5G 802.11ac, or 2.4G/5G 802.11n WLAN applications
- Backward compatible with 802.11a/b/g device
- Support IEEE 802.11e QoS Enhancement and 802.11i (WPA, WPA2)
- Support IEEE 802.11h DFS
- Wi-Fi Direct supports wireless peer to peer applications
- Single external power source 3.3V only

### PHY Features

- Maximum PHY data rate up to 86.7MHz using 20MHz bandwidth, 200Mbps using 40Mhz bandwidth and 433.3Mbps using 80Mhz bandwidth

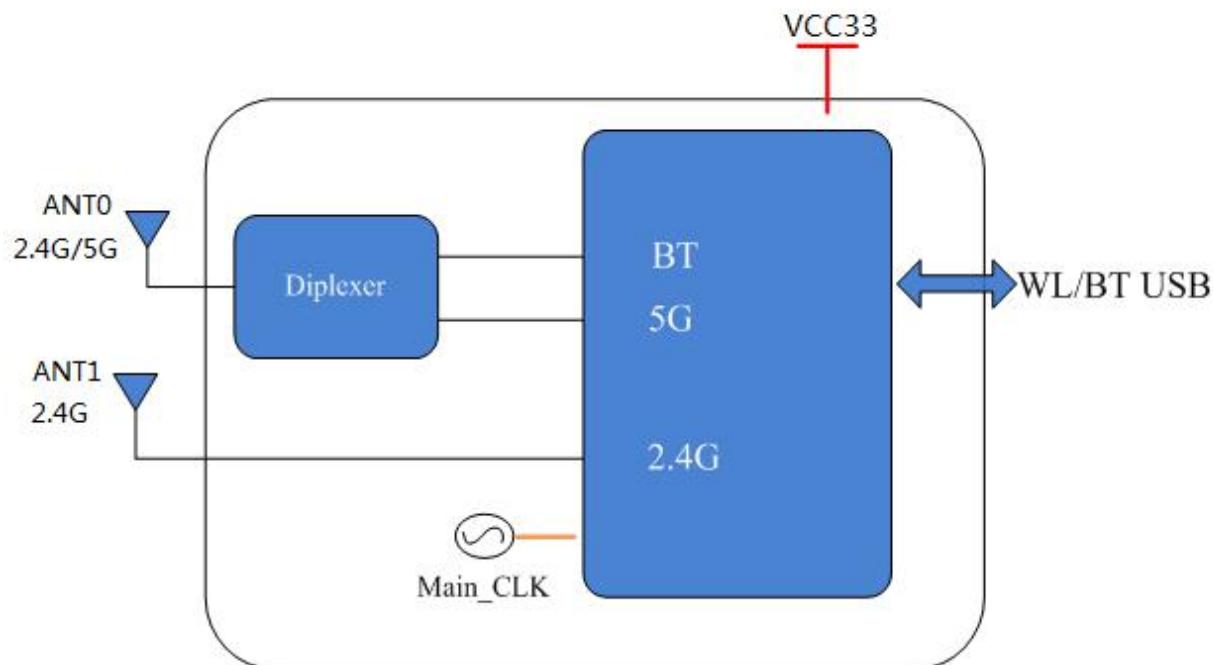
### Host Interface

- USB Multi-Function for both BT and WLAN

### Bluetooth Features

- Supports Bluetooth 4.2 and backward compatible with Bluetooth 2.1 + EDR
- Bluetooth 4.0 Dual Mode support: Simultaneous LE and BR/EDR
- Supports Bluetooth Low Energy
- Integrated internal Class 1, Class 2 and Class 3 PA for Bluetooth
- Support Bluetooth5.0 high duty cycle Non-connectable advertising.

### 3. Block Diagram



### 4. General Specification

#### 4.1 2.4GHz WI-FI Specification

Feature	Description	
WLAN Standard	IEEE 802.11 b/g/n Wi-Fi compliant	
Test Items	Typical Value	EVM
Output Power <sup>1</sup>	802.11b /11Mbps : 16dBm ± 2 dBm 1M bps: 17 dBm± 2 dBm	EVM ≤ -9dB MASK compliant
	802.11g /54Mbps : 15dBm ± 2 dBm 6Mbps : 17dBm± 2 dBm	EVM ≤ -26dB MASK compliant
	802.11n /MCS7 : 14dBm ± 2 dBm MCS0 : 17dBm ± 2 dBm	EVM ≤ -28dB MASK compliant

Spectrum Mask	Meet with IEEE standard		
Freq. Tolerance	$\pm 20\text{ppm}$		
Receive Sensitivity (11b,20MHz) @8% PER	- 1Mbps	PER @ -92 dBm	$\leq -83$
	- 11Mbps	PER @ -85 dBm	$\leq -76$
Receive Sensitivity (11g,20MHz) @10% PER	- 6Mbps	PER @ -89 dBm	$\leq -85$
	- 54Mbps	PER @ -71 dBm	$\leq -68$
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0	PER @ -89 dBm	$\leq -85$
	- MCS=7	PER @ -69 dBm	$\leq -67$
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0,	PER @ -87 dBm	$\leq -82$
	- MCS=7,	PER @ -67 dBm	$\leq -64$

1.low rate power controlled by firmware driver;

## 4.2 5GHz WI-FI Specification

Feature	Description	
WLAN Standard	IEEE 802.11a/n/ac, Wi-Fi compliant	
Frequency Range	4.900 GHz ~ 5.845 GHz (5.0 GHz ISM Band)	
Number of Channels	5.0GHz: Please refer to the table <sup>1</sup>	
Modulation	802.11a/n: 64-QAM,16-QAM, QPSK, BPSK	EVM
	802.11ac: 256-QAM, 64-QAM,16-QAM, QPSK, BPSK	MASK compliant
Test Items	Typical Value	EVM
Output Power <sup>2</sup>	802.11g /54Mbps : $14\text{dBm} \pm 2\text{ dBm}$	$\text{EVM} \leq -27\text{dB}$
	6Mbps : $16\text{dBm} \pm 2\text{ dBm}$	MASK compliant
	802.11n /MCS7 : $13\text{dBm} \pm 2\text{ dBm}$	$\text{EVM} \leq -29\text{dB}$
	MCS0 : $16\text{dBm} \pm 2\text{ dBm}$	MASK compliant
	802.11ac /MCS7 : $13\text{dBm} \pm 2\text{ dBm}$	$\text{EVM} \leq -29\text{dB}$
	MCS0 : $16\text{dBm} \pm 2\text{ dBm}$	MASK compliant
	802.11ac/MCS9: $10\text{ dBm} \pm 2\text{ dBm}$	$\text{EVM} \leq -33\text{dB}$
Receive Sensitivity (11a) @10% PER	- 6Mbps:	$\text{PER} \leq -86\text{ dBm}$
	- 54Mbps:	$\text{PER} \leq -70\text{ dBm}$
Receive Sensitivity (11n,20MHz) @10% PER	- MCS=0:	$\text{PER} \leq -85\text{ dBm}$
	- MCS=7:	$\text{PER} \leq -67\text{ dBm}$
Receive Sensitivity (11n,40MHz) @10% PER	- MCS=0:	$\text{PER} \leq -83\text{ dBm}$
	- MCS=7:	$\text{PER} \leq -64\text{ dBm}$
Receive Sensitivity (11ac,20MHz) @10% PER	- MCS=0:	$\text{PER} \leq -86\text{ dBm}$
	- MCS=8:	$\text{PER} \leq -63\text{ dBm}$

Receive Sensitivity (11ac,40MHz) @10% PER	- MCS=0: PER $\leq -83$ dBm - MCS=9: PER $\leq -59$ dBm
Receive Sensitivity (11ac,80MHz) @10% PER	- MCS=0: PER $\leq -80$ dBm - MCS=9: PER $\leq -56$ dBm

2.low rate power controlled by firmware driver;

<sup>1</sup>5GHz Channel table

Band (GHz)	Operating Channel Number	Channel Center Frequency(MHz)
5.15GHz~5.25GHz	36	5180
	40	5200
	44	5220
	48	5240
5.25GHz~5.35GHz	52	5260
	56	5280
	60	5300
	64	5320
5.5GHz~5.7GHz	100	5500
	104	5520
	108	5540
	112	5560
	116	5580
	120	5600
	124	5620
	128	5640
	132	5660
	136	5680
5.725GHz~5.825GHz	140	5700
	149	5745
	153	5765
	157	5785
	161	5805
	165	5825

### 4.3 Bluetooth Specification

Feature	Description
<b>General Specification</b>	
Bluetooth Standard	Bluetooth V5.0

Host Interface	USB 2.0
Antenna Reference	Small antennas with 0~2 dBi peak gain
Frequency Band	2402 MHz ~ 2480 MHz
Number of Channels	79 channels
Modulation	GFSK, $\pi/4$ -DQPSK, 8-DPSK

### RF Specification

	Min(dBm)	Typical(dBm)	Max(dBm)
Output Power (Class 1)	4	8	12
Sensitivity @ BER=0.1% for GFSK (1Mbps)		-88	
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)		-85	
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)		-81	
Maximum Input Level	GFSK (1Mbps):-20dBm		
	$\pi/4$ -DQPSK (2Mbps) :-20dBm		
	8DPSK (3Mbps) :-20dBm		

## 5. ID setting information

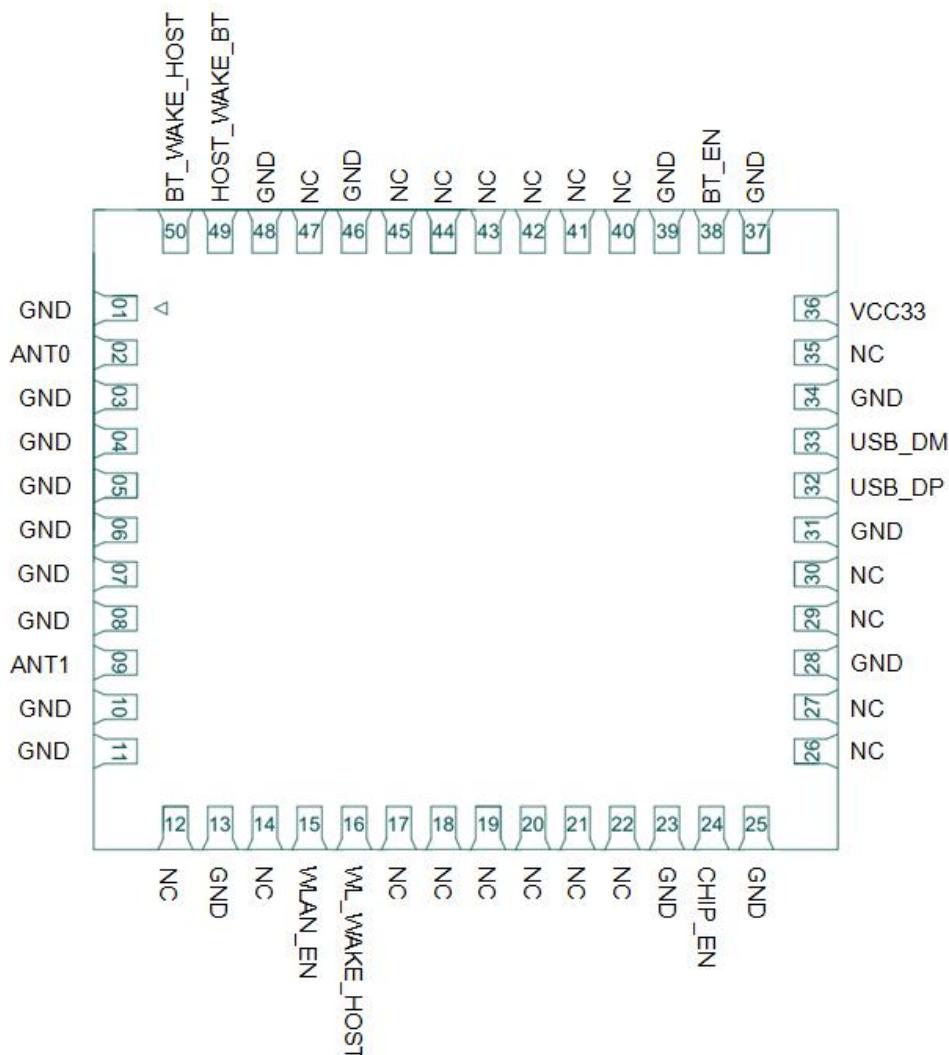
### WI-FI

Vendor ID	-
Product ID	-

## 6. Pin Definition

### 6.1 Pin Outline

< TOP VIEW



### 6.2 Pin Definition details

No.	Name	Type	Description	Voltage
1	GND	—	Ground connections	
2	ANT0	I/O	RF I/O chain0, Wi-Fi 5GHz and BT	
3~8	GND	—	Ground connections	

9	ANT1	I/O	RF I/O chain1, Wi-Fi 2.4GHz	
10~11	GND	—	Ground connections	
12	NC	—	Not connected	
13	GND	—	Ground connections	
14	NC	—	Not connected	
15	WLAN_EN	I	Enable pin for WLAN device ON: pull high ; OFF: pull low	3.3V
16	WL_WAKE_HOST	O	WLAN to wake-up HOST	3.3V
17~22	NC	—	Not connected	
23	GND	—	Ground connections	
24	CHIP_EN	I/O	Enable pin for chipset. Pull low to shut down RTL8821CU. (Internal 47Kohm pull-high to 3.3V)	3.3V
25	GND	—	Ground connections	
26~27	NC	—	Not connected	
28	GND	—	Ground connections	
29~30	NC	—	Not connected	
31	GND	—	Ground connections	
32	USB_DP	I/O	USB2.0 differential pair D+ for WLAN and Bluetooth	
33	USB_DM	I/O	USB2.0 differential pair D- for WLAN and Bluetooth	
34	GND	—	Ground connections	
35	NC	—	Not connected	
36	VCC33	P	Main power input 3.3V	3.3V
37	GND	—	Ground connections	
38	BT_EN	I	Enable pin for Bluetooth device ON: pull high ; OFF: pull low	3.3V
39	GND	—	Ground connections	
40~45	NC	—	Not connected	
46	GND	—	Ground connections	
47	NC	I	Not connected	
48	GND	—	Ground connections	
49	HOST_WAKE_BT	I	HOST to wake-up Bluetooth device	3.3V
50	BT_WAKE_HOST	O	Bluetooth device to wake-up HOST	3.3V

P:POWER I:INPUT O:OUTPUT VDDIO:3.3V

## 7. Electrical Specifications

### 7.1 Power Supply DC Characteristics

	MIN	TYP	MAX	Unit
Operating Temperature	0	25	70	deg.C
Power Supply (VCC)	3.135	3.3	3.465	V

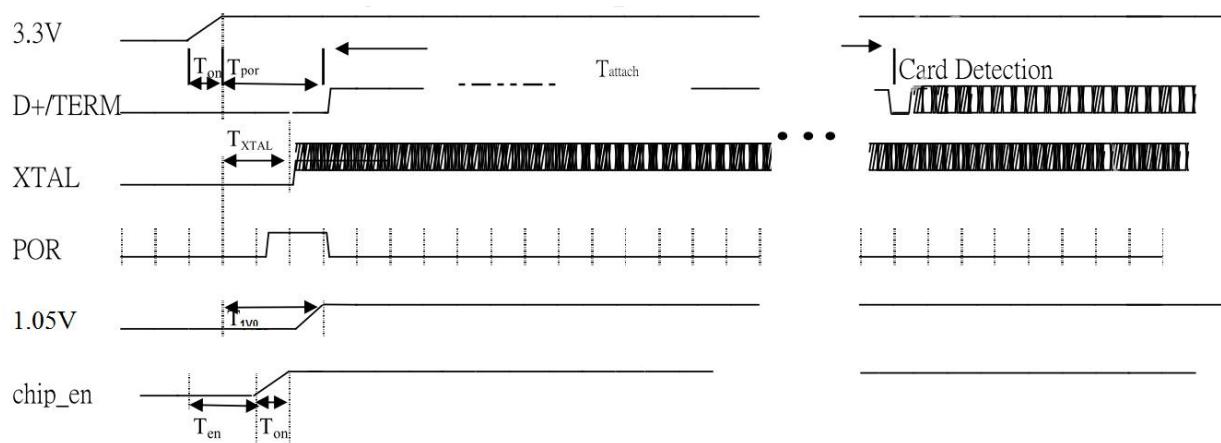
### 7.2 Power Consumption

Condition	Current Consumption(mA)
WLAN/BT Disabled	2
Wi-Fi 5G associated	93
TX throughput (5G 11ac VHT80)	264
RX throughput (5G 11ac VHT80)	136
TX throughput (5G 11n HT20)	320
RX throughput (5G 11n HT20)	107
TX throughput (5G 11a OFDM54)	266
RX throughput (5G 11a OFDM54)	130
TX throughput (2.4G 11n HT40)	291
RX throughput (2.4G 11n HT40)	115
TX throughput (2.4G 11b CCK11)	283
RX throughput (2.4G 11b CCK11)	141

Typical Power Consumption  
(VCC=3.3V; BT on if no other statement)

## 7.3 Interface Circuit time series

### 7.3.1 USB Bus Timing during Power On Sequence



**T<sub>on</sub>:** the main power ramp on duration

**T<sub>por</sub>:** the power on reset releases and power management unit executes power on tasks

**T<sub>attach</sub>:** USB attach state

**T<sub>xtal</sub>:** XTAL starts

**T<sub>en</sub>:** interval between the rising point of 3.3V and chip\_en

#### The power on flow description:

After main 3.3V ramp up, the internal power on reset is released by power ready detection circuit and the power management unit will be enabled. The power management unit enables the internal regulator and clock circuits.

The power management unit also enables the USB circuits.

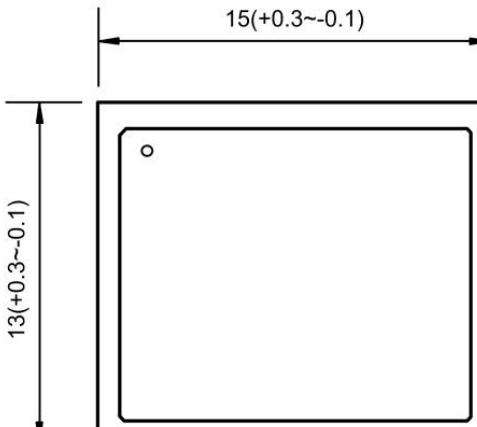
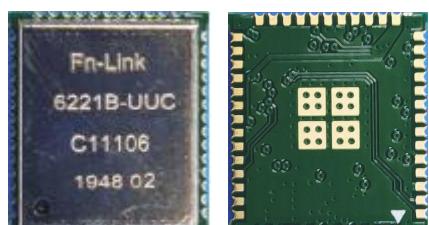
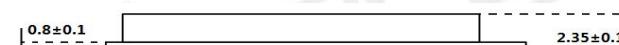
USB analog circuits attach resistors to indicate the insertion of the USB device.

#### The typical timing range:

	Unit	Min	Typical	Max
<b>T<sub>on</sub></b>	ms	--	1.5	5
<b>T<sub>por</sub></b>	ms	--	2	20
<b>T<sub>xtal</sub></b>	ms	--	1.5	8
<b>T<sub>attach</sub></b>	ms	100	250	--
<b>T<sub>1v0</sub></b>	ms	--	3	11
<b>T<sub>en</sub></b>	ms	0	0	5

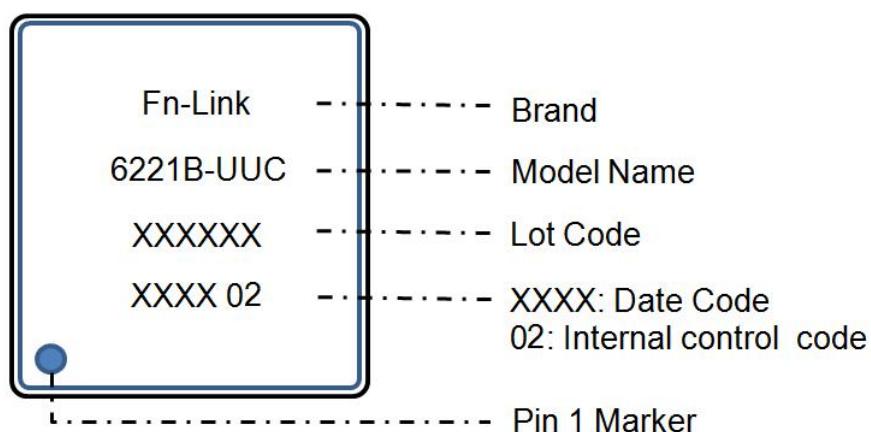
## 8. Size reference

### 8.1 Module Picture

L x W : 15 x 13(+0.3/-0.1) mm	
	
H: 2.35 ( $\pm 0.2$ ) mm	
<b>Weight</b>	0.92g

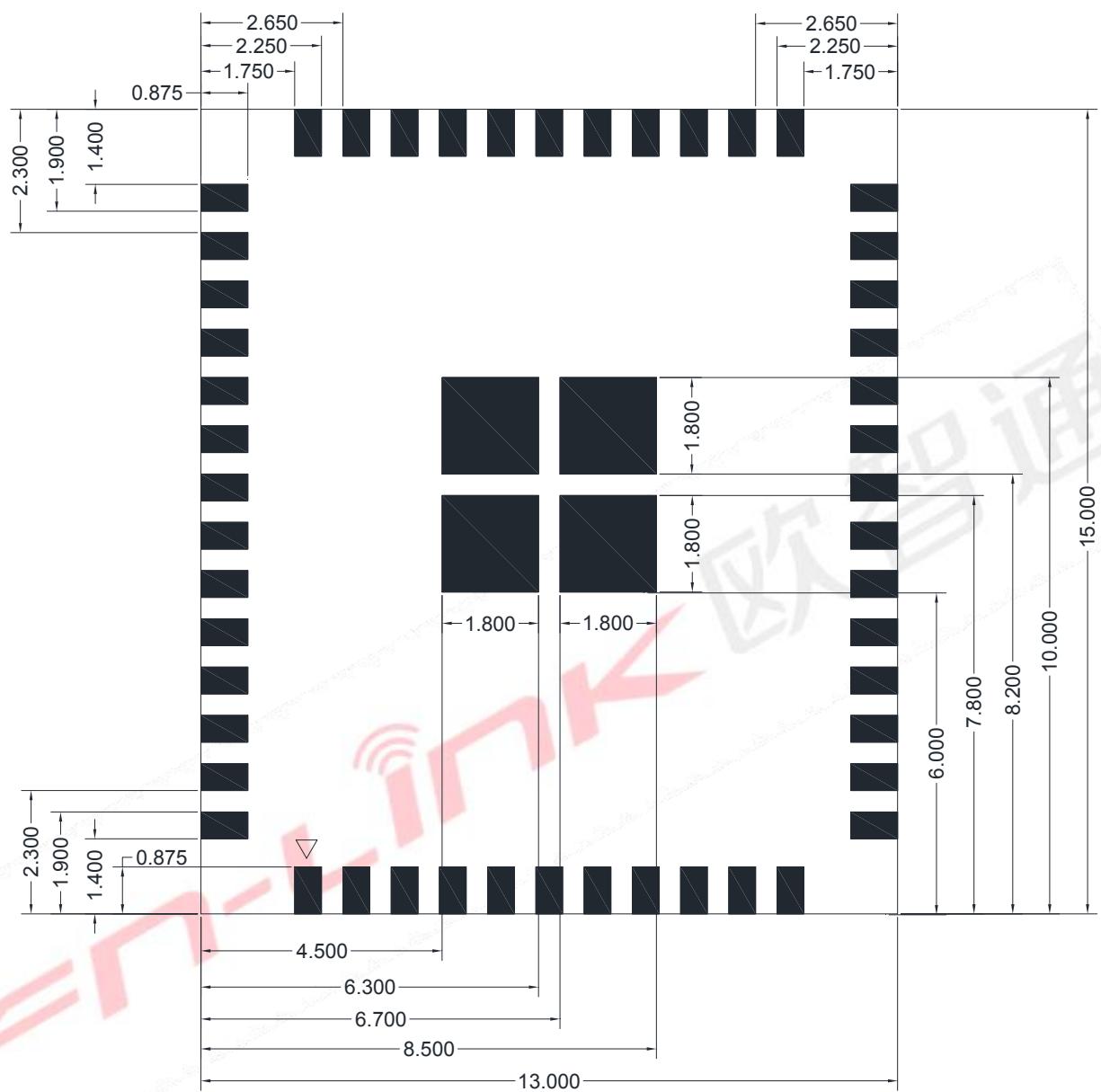
### 8.2 Marking Description

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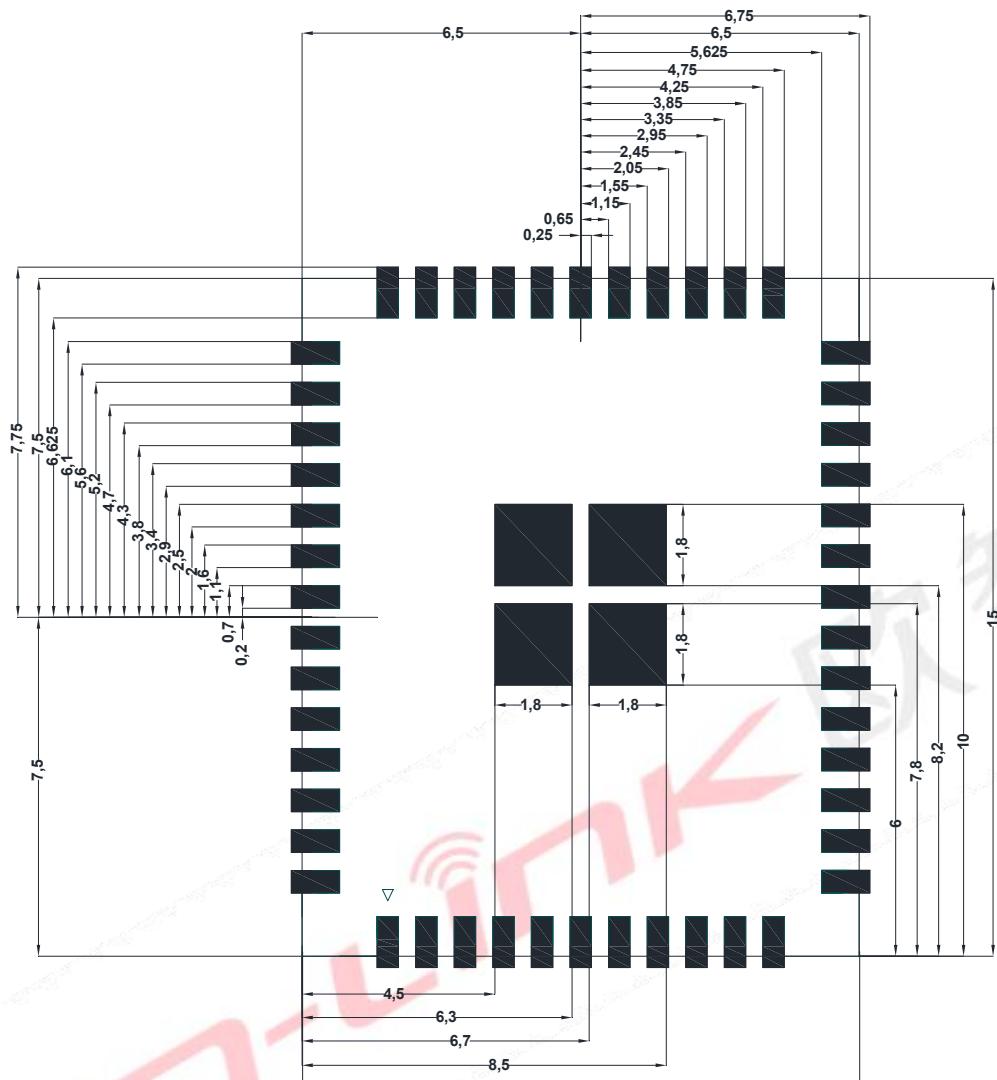


### 8.3 Physical Dimensions

<TOP View>



## 8.4 Layout Recommendation

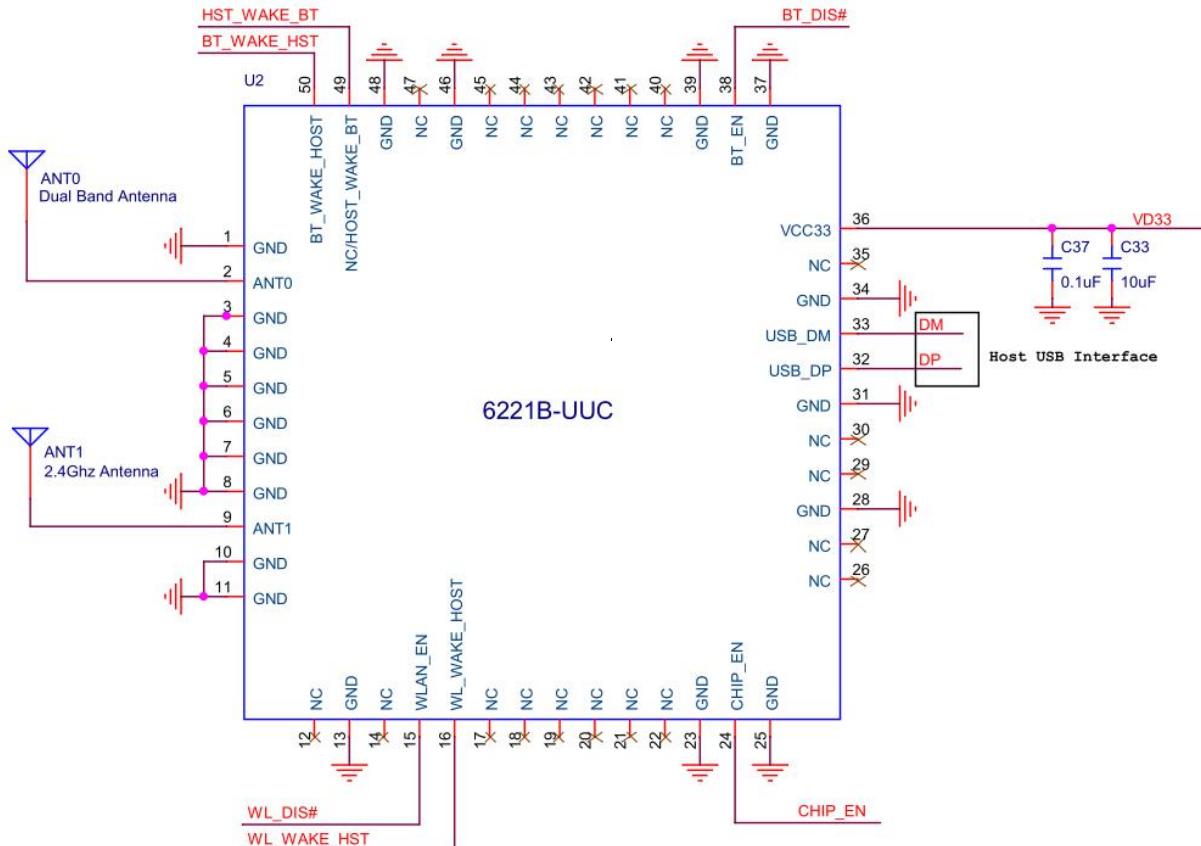


## 9. The Key Material List

Chipset	RTL8821CU-VB	Realtek
PCB	6221B-UUC 15x13x0.8mm 4L	XY-PCB,KX-PCB,SL-PCB,Sunlord
TVS	0201 4V 0.05pF 15KV TVS	Murata, way-on
DPX	Multilayer Chip Diplexers,Dual-band 2.4GHz/5GHz,3W,1.0×0.5-0.45mm	ACX,walsin,Glead,murata,TDK
Crystal	2520 40MHZ 15PF, 10ppm	TST,HOSONIC,TKD,ECEC,JWT

Inductor	0603 2.2UH, $\pm 20\%$ 850mA	Microgate,sunlord,cenke,ceaiya
Shielding	6221B-UUC shielding	信太,精力通

## 10. Reference Design



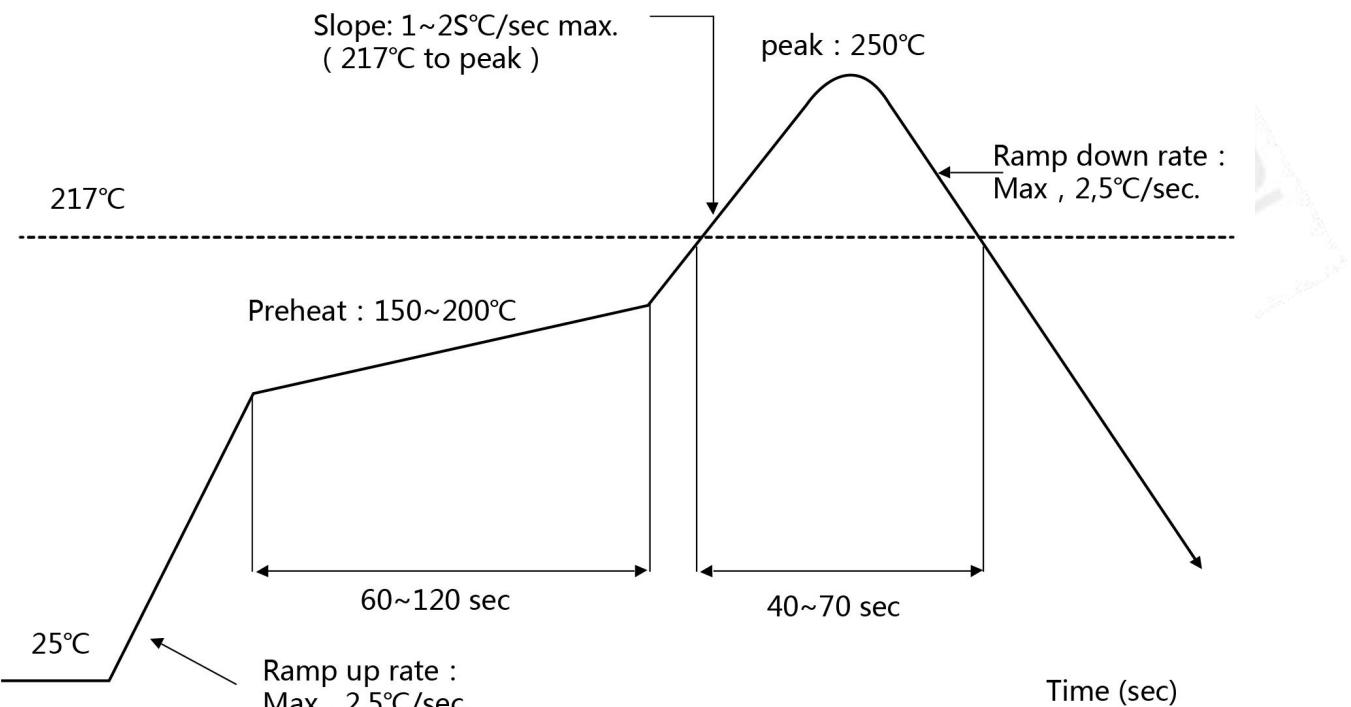
Note: Module requires independent power supply , supply capacity  $\geq 600\text{mA}$  and ripple less than  $100\text{mV}$ ;  
 Do not share power with amplifier, infrared device, camera, etc.  
 RF port between module and antenna better implement pi circuit for matching.

## 11. Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : <250°C

Number of Times : ≤2 times



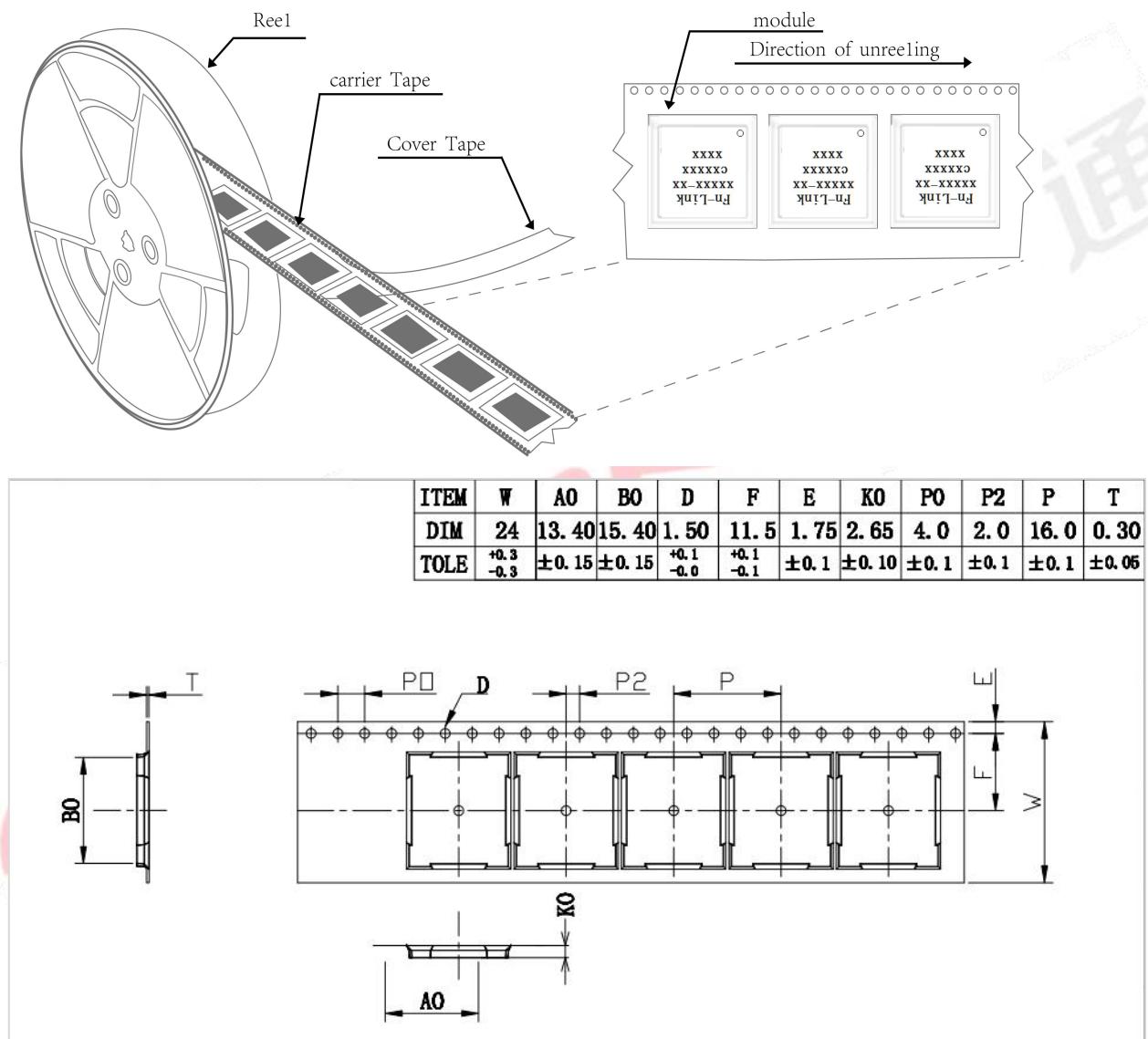
## 12. RoHS compliance

All hardware components are fully compliant with EU RoHS directive

## 13. Package

### 13.1 Reel

A roll of 1500pcs



### 13.2 Packaging Detail

the take-up package



Using self-adhesive tape

Color of plastic disc: blue



NY bag size:TBD



Internal boxsize : TBD



The packing case size:TBD

## 14. Moisture sensitivity

The Modules is a Moisture Sensitive Device level 3, in according with standard IPC/JEDEC J-STD-020, take care

all the relatives requirements for using this kind of components.

Moreover, the customer has to take care of the following conditions:

- a) Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- b) Environmental condition during the production: 30°C / 60% RH according to IPC/JEDEC J-STD-033A paragraph 5
- c) The maximum time between the opening of the sealed bag and the reflow process must be 168 hours if condition
- b) "IPC/JEDEC J-STD-033A paragraph 5.2" is respected
- d) Baking is required if conditions b) or c) are not respected
- e) Baking is required if the humidity indicator inside the bag indicates 10% RH or more